SPECIFICATION FOR APPROVAL

DESCRIPTION: Pitch 0.50mm NON-ZIF FPC Connector, R/A, SMT Type Dual Contact

CUSTOMER PROD.NO/DWG.NO:

E&T PROD.NO:

7084K-YXXN-00X

APPROVAL SHEET NO:

E&T DWG. NO./DOCUMENT: 7084K-YXXN-00X

REV: A1

PLEASE RETURN TO US ONE COPY OF"SPECIFICATION FOR APPROVAL"WITH YOUR APPROVED SIGNATURES.

APPROVED SIGNATURES								



ENTERY INDUSTRIAL CO., LTD. E&T ELECTRONICS (DONG GUAN) CO., LTD. E&T ELECTRONICS (SU ZHOU) CO., LTD. E&T ELECTRONICS (NANKEEN)CO.,LTD.



Title : Pitch 0.50mm NON-ZIF FPC Connector, R/A, SMT Type Dual Contact

RELEASE Title: Pitch 0.50mm NON-ZIF FPC Connector, R/A, SMT Type Dual Contact HISTORY Title: Pitch 0.50mm NON-ZIF FPC Connector, R/A, SMT Type Dual Contact							
A1 Dav	08,09,2011 Description		This Document Contains Information That Is Proprietary To E&T And Should Not Be Used Without Written Permission				
Rev Documen	-	Prepared By: Well Liu Date: 06,22,2011					
7084K-YXXN-00X		N-00X	Approved By: Jab Sam (11)	Date: $q_1/5_2 > 011^{\prime}$ Date: $q_1/5_2 > 011^{\prime}$			

GROUP AND TEST SEQUENCE

	Test of Examination		Test Group											
			В	С	D	Е	F	G	Η	Ι	J	K	L	М
1	Examination of Product	1,9	1,6	1,5	1,5	1,5	1,4	1,5	1,3	1,3	1,5			
2	Contact Resistance	2,6	2,5	2,4	2,4	2,4		2,4			2,4			
3	Insulation Resistance	3,7												
4	Dielectric Strength	4,8												
5	Mating and Unmating Force Test		3											
6	Terminal / Housing Retention Force											1		
7	Fix Pin / Housing Retention Force												1	
8	Durability		4											
9	Vibration			3										
10	Heat Resistance				3									
11	Cold Resistance					3								
11	Humidity	5												
13	Solder Ability						3		2					
14	Resistance To Soldering Heat									2				
15	Steam Aging						2							
16	Salt Spray							3						
17	Temperature Cycling										3			
18	Dimension													1

PRODUCT SPECIFICATION

1. SCOPE :

This specification covers the pitch 0.5 mm NON-ZIF FPC connector series.

2. PRODUCT NAME AND PART NUMBER :

Product Name	E&T Part Number
0.50mm NON-ZIF FPC Connector, R/A, SMT Type Dual Contact	7084K-YXXN-00X

3. RATINGS :

Item	Standard	
Rated Voltage (MAX.)	50 V	DC
Rated Current (MAX.)	0.5A	DC
Operating Temperature Range	-40 ⁰	C ~ +80 ⁰ C

*Including terminal temperature rise

4.PERFORMANCE :

4-1 Electrical Performance

	Item	Test Condition	Requirement
4-1-1	Contact Resistance	Test Current: 1 mA Max. Test Voltage: 20mV Max Test Method:EIA-364-06B	40 mΩ MAX.
4-1-2	Insulation	Test Voltage: 100V DC. Test Duration: 1 minutes.	Initial: 500 M Ω Min
4-1-2	Resistance	Test Method:EIA-364-21C	
4-1-3	Dielectric Strength	Test Voltage: 200V AC. Test Time: 60 sec. Test Method:EIA-364-09C	No Breakdown

4-2 Mechanical Performance

	Item	Test Condition	Requirement
4-2-1	Mating and Unmating Force Test	Test Speed: 25±3 mm/min. Test Method:EIA-364-38B	Mating Force 0.15kgf/ per pin (Initial) Unmating Force 0.02kgf/ per pin
4-2-2	Terminal / Housing Retention Force	Test Speed: 25mm/min.	0.1kgf (Min)
4-2-3	Fix Pin / Housing Retention Force	Test Speed: 25mm/min.	0.3kgf (Min)

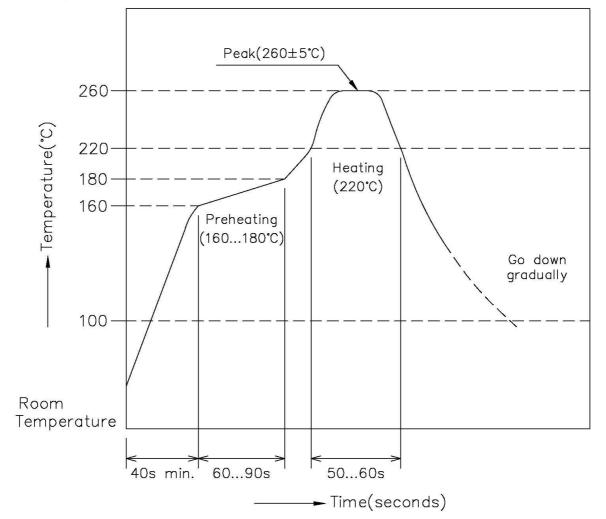
4-3 Environmental Performance and Others

	Item	Test Condition	Require	ment
		Insert and withdraw actuator up to 30cycles at the speed rate of less than 10 cycles/	Contact Resistance	
4-3-1	Durability	minute.	Initial Value	\leq 40 m Ω
		Test Method:EIA-364-09C	Final Value	\leq 60 m Ω
		Amplitude : 1.5 mm Frequency range: 10~55~10 Hz in 1 minute	Appearance	No Damage
4-3-2	Vibration	Duration: 2 hours in each X.Y.Z axes Current: 100mA. Test Method:EIA-364-28D	Contact Resistance	\leq 60 m Ω
			Discontinuity	1µsec
4-3-3	Heat	Temperature: 80±2°C Duration: 96 hours	Appearance	No Damage
100	Resistance		Contact Resistance	\leq 60 m Ω
4-3-4	Cold	Temperature: -40±2°C Duration: 96 hours	Appearance	No Damage
4-0-4	Resistance		Contact Resistance	\leq 60 m Ω
		Temperature: 40±2℃ Relative Humidity: 90~95%	Appearance	No Damage
4-3-5	Humidity	Duration: 96 hours Test Method:EIA-364-31B	Contact Resistance	\leq 60 mΩ
	Tarmany		Insulation Resistance	\geq 500MQ
			Dielectric Strength	Must meet 4-1-3

	Item	Test Condition	Requ	irement
4-3-6	Solder Ability	Soldering Time : 3±0.5 sec Solder Temperature : 245±5℃ Test Method:EIA-364-52	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-7	Resistance To Soldering Heat	Soldering Time : 10±0.5 sec Solder Temperature : 260±5°C Test Method:EIA-364-56C	Appearanc	e No Damage
		Steam Aging Temperature : 98±2°C Duration: 8 hours Solder Temperature : 235±5°C Soldering Time : 2±0.5 acc	Appearanc	e No Damage
4-3-8	Steam Aging	Soldering Time : 3±0.5 sec Test Method:EIA-364-17B	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-9	Salt Spray	Chamber Temperature : $35\pm2^{\circ}$ C Air Tank Temperature : $47\pm1^{\circ}$ C Salt Solution : $5\pm0.5\%$ Duration : 48 hours	Appearanc	e No Damage
+ 0 0	Sull Oplay	Test Method:EIA-364-26B	Contact Resistance	$\leq 60 \text{ m}\Omega$
4-3-10	Temperature	5 cycles of : a) - 55 ±3℃ 30 minutes b) +25 ±3℃ 30 minutes	Appearanc	e No Damage
+-0-10	Cycling	c)+ 85 ±2°C 30 minutes Test Method:EIA-364-31B	Contact Resistance	$\leq 60 \text{ m}\Omega$

INFRARED REFLOW CONDITION

- 1) Ascending time to preheating temperature 170°C shall be 40 seconds minimur
- 2) Preheating shall be fixed at 160...180°C for 60...90 seconds.
- 3) Heating shall be fixed at 220°C for 50...60 seconds.
- 4) At $260\pm5^{\circ}$ C peak shall be 10 seconds maximum.



Non-ZIF FPC /FFC Connector Handling Precautions

This manual is to describe basic precautions. When there are doubtful points in use of, please contact E&T.

1. Common Handling Precautions

- Do not expose E&T's Non-ZIF FPC/FFC connector, processing process product and processing product to corrosive substance, corrosive gas, high temperature and high humidity and direct sunshine. It causes corrosion of contact and deterioration of insulation performance of housing, etc., so that it causes motion defect of appliances.
- Do not apply external load to E&T's Non-ZIF FPC/FFC connector, processing process product and processing product . Deformation and breakage, etc. occur, and it causes performance defect of.
- There may be slight differences in the housing coloring, but there will be no influence on the product's performance.
- Please add a stiffener on the flexible printed circuit (FPC/FFC) when you mount the connector onto FPC in order to prevent deformation of the FPC/FFC.
- Please do not conduct any "washing process" on the connector because it may damage the product's function.

2. PC Board Precautions

- Exercise caution when handling boards with the connectors installed. Do not apply any forces affecting soldered joints. (see figure 1).
- The mounting specification for coplanarity does not include the influence of warpage of the printed circuit board. (see figure 1).

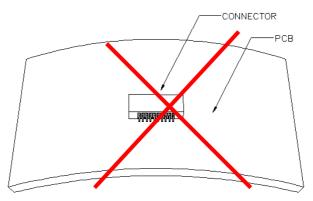
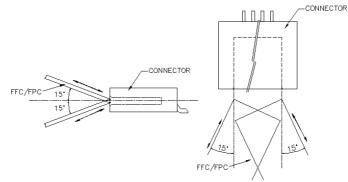


Figure 1.

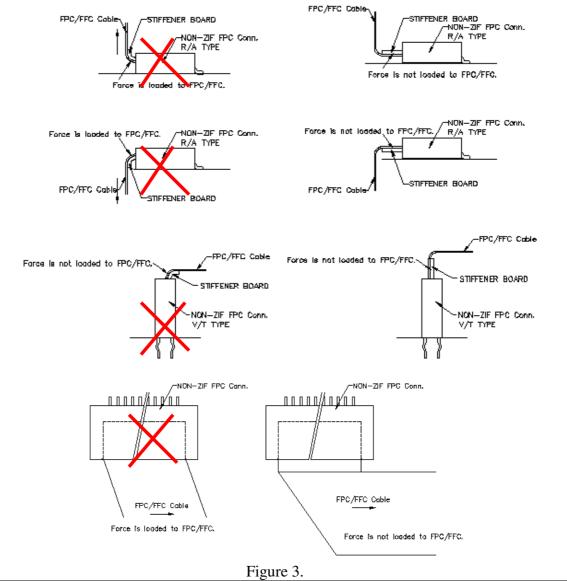
3. Precautions When Inserting or Withdrawal FPC/FFC

• FPC/FFC to be insertion and withdrawal at an angle of about 15°, and the FPC/FFC should be inserted firmly all the way to the back. (see figure 2).





- Do not apply any forces affecting soldered joints. Do not apply upward pull-force to the FPC/FFC close to the connector. (see figure 3).
- If necessary, please fix the FPC/FFC directly on the chassis. Also, please avoid pulling the FPC/FFC vertically or twisting the FPC back and force horizontally while it is inserted in the connector(see figure 3).
- Forming processing is conducted to FPC so as not to load force to connector. (see figure 3).



ENTERY INDUSTRIAL CO., LTD. RELEASE HISTORY

Rev.	Revisions	Date	Executor	Description
A1	RE201108011	AUG-09-2011	KAZ	ADD Handling Precautions